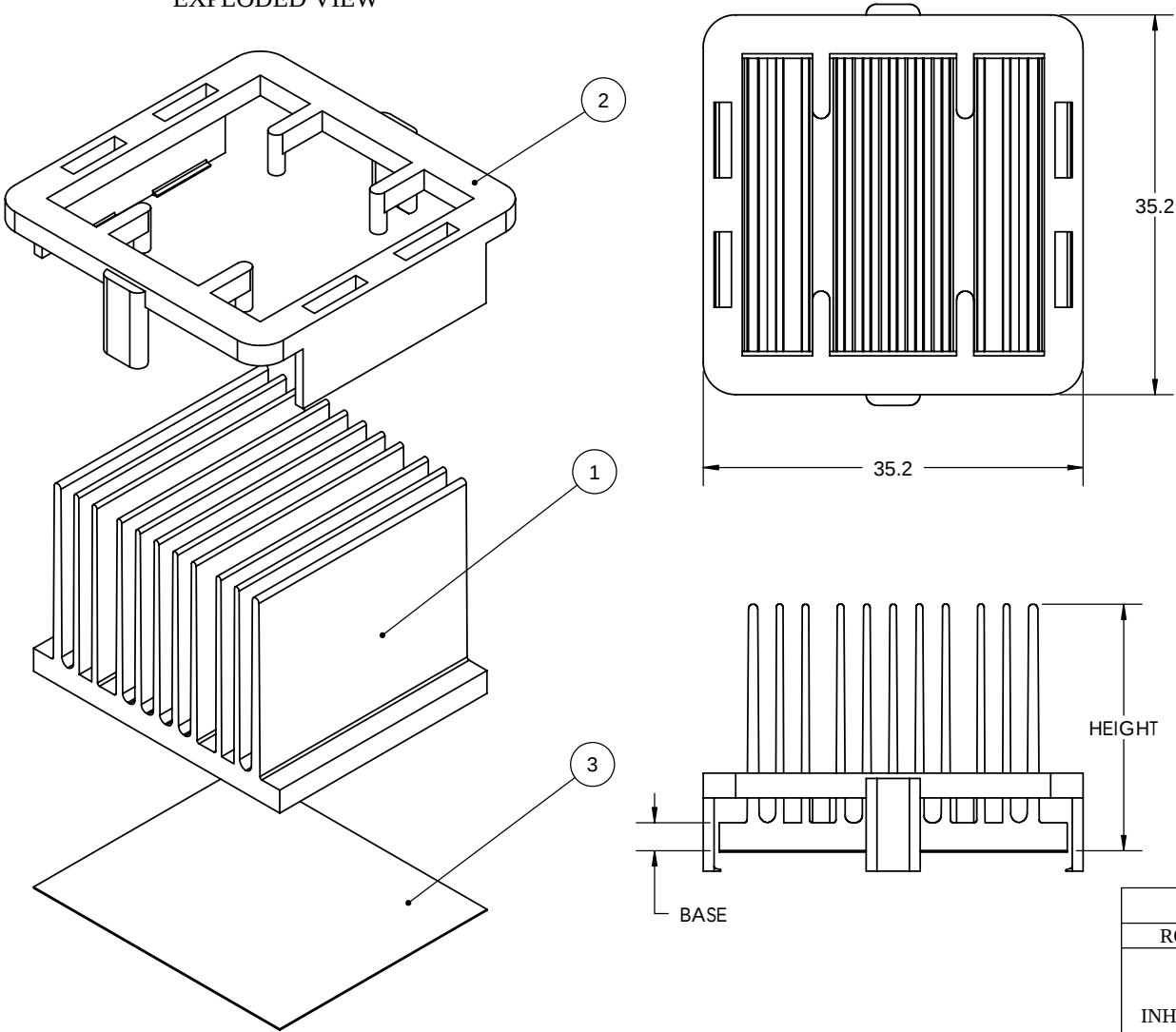


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REV	DESCRIPTION OF REVISIONS	APPROVED	DATE
A	INITIAL RELEASE	FWANG	10/26/07
B	PER ECN#801081	AREDDY	01/08/01

EXPLODED VIEW



CHIP HEIGHT	CLIP
3.3±0.3MM	BCP35-09(33)Y
2.6±0.3MM	K33
1.7±0.3MM	BCP35-09(33)BU
0.9±0.3MM	BCP35-09(33)O

NOTES:
1. CUSTOMER TO SPECIFY HEIGHT, BASE, TYPE OF CLIP AND PAD.
2. RECOMMENDED KEEP-OUT AREA: 38X38 MM.
3. CLIP SELECTION IS BASED ON THE CHIP HEIGHT (EXCLUDING THE SOLDER BALL HEIGHT OF 0.25MM)

COMPLETE PART NUMBER WITH OPTIONS				
ROOT	HEIGHT	BASE	CLIP	PAD
INH33001-	12 (MM)	/2.6 (MM)	K33	+T710
	15 (MM)		Y	
	18 (MM)	/OTHER (MM)	BU	+OTHER
	23 (MM)		O	
	OTHER (MM)			

EXAMPLE PART NUMBER: INH33001-23/2.6BU+T710

ITEM NO.	PART NUMBER	DESCRIPTION	QTY.
1	INH33001-hh	33MM PLATE FIN HEATSINK (SEE TABLE ON THE RIGHT FOR HEIGHT CODE hh)	1
2	OPTIONAL	33 MM EZ-SNAP CLIP (SEE TABLE ON THE RIGHT UNDER CLIP)	1
3	OPTIONAL	THERMAL PAD 1.27X1.07"	1

MATERIAL		APPROVALS		DATE		 RADIAN HEATSINKS DIV. OF INTRICAST CO. INC. 2160 WALSH AVE SANTA CLARA, CA 95050
FINISH		DRAWN		10/26/07		
CHECKED		FWANG		10/26/07		
MFG ENG		QUAL ENG				
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MM TOLERANCES ARE: 1 PLACE DECIMALS: ± 0.25 2 PLACE DECIMALS: ± 0.10 ANGLES: ± 1°		THIRD ANGLE PROJECTION		33 MM HEAT SINK ASSEMBLY		
				SIZE DWG. NO.		REV.
				A INH33001		B
SHEET 1 OF 1						